

# N0603N

# N-CHANNEL MOSFET FOR SWITCHING

R07DS0559EJ0100 Rev.1.00 Nov 07, 2011

#### **Description**

The N0603N is N-channel MOS Field Effect Transistor designed for high current switching applications.

#### **Features**

• Low on-state resistance

$$R_{DS \text{ (on)}} = 4.6 \text{ m}\Omega \text{ MAX.} (V_{GS} = 10 \text{ V}, I_D = 50 \text{ A})$$

• Low input capacitance

$$C_{iss} = 7730 \text{ pF TYP.} (V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V})$$

• High current

$$I_{D(DC)} = \pm 100 \text{ A}$$

• RoHS Compliant

## **Ordering Information**

Part No.	Lead Plating	Packing	Package
N0603N-S23-AY*1	Pure Sn (Tin)	Tube	TO-262
		50 p/tube	1.8 g TYP.

Note: \*1. Pb-free (This product does not contain Pb in the external electrode.)

## Absolute Maximum Ratings ( $T_A = 25^{\circ}C$ , all terminals are connected)

Item	Symbol	Ratings	Unit
Drain to Source Voltage (V <sub>GS</sub> = 0 V)	$V_{DSS}$	60	V
Gate to Source Voltage (V <sub>DS</sub> = 0 V)	$V_{GSS}$	±20	V
Drain Current (DC)	I <sub>D(DC)</sub>	±100	Α
Drain Current (pulse) *1	I <sub>D(pulse)</sub>	±400	Α
Total Power Dissipation (T <sub>C</sub> = 25°C)	P <sub>T1</sub>	156	W
Total Power Dissipation (T <sub>A</sub> = 25°C)	P <sub>T2</sub>	1.5	W
Channel Temperature	T <sub>ch</sub>	150	°C
Storage Temperature	T <sub>stg</sub>	-55 to +150	°C
Single Avalanche Current *2	I <sub>AS</sub>	55	A
Single Avalanche Energy *2	E <sub>AS</sub>	300	mJ

### **Thermal Resistance**

Channel to Case (Drain) Thermal Resistance  $R_{th(ch-C)}$  0.80 °C/W Channel to Ambient Thermal Resistance \*2  $R_{th(ch-A)}$  83.3 °C/W

Notes: \*1. PW  $\leq$  10  $\mu$ s, Duty Cycle  $\leq$  1%

\*2. Starting  $T_{ch}$  = 25°C,  $R_G$  = 25  $\Omega$ ,  $V_{DD}$  = 30 V,  $V_{GS}$  = 20  $\rightarrow$  0 V, L = 100  $\mu H$ 

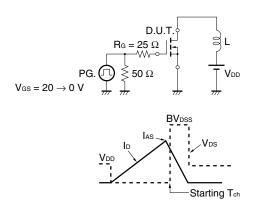
# Electrical Characteristics ( $T_A = 25$ °C, all terminals are connected)

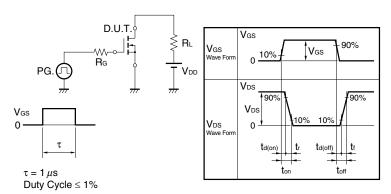
Item	Symbol	MIN.	TYP.	MAX.	Unit	Test Conditions
Zero Gate Voltage Drain Current	I <sub>DSS</sub>			1	μΑ	V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V
Gate Leakage Current	I <sub>GSS</sub>			±100	nA	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$
Gate to Source Cut-off Voltage	$V_{GS(off)}$	2.0		4.0	V	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}$
Forward Transfer Admittance *1	y <sub>fs</sub>	35			S	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 50 A
Drain to Source On-state Resistance *1	R <sub>DS(on)</sub>		3.7	4.6	mΩ	$V_{GS} = 10 \text{ V}, I_{D} = 50 \text{ A}$
Input Capacitance	C <sub>iss</sub>		7730		pF	V <sub>DS</sub> = 25 V,
Output Capacitance	Coss		560		pF	$V_{GS} = 0 V$ ,
Reverse Transfer Capacitance	C <sub>rss</sub>		290		pF	f = 1 MHz
Turn-on Delay Time	t <sub>d(on)</sub>		35		ns	$V_{DD} = 30 \text{ V}, I_D = 50 \text{ A},$
Rise Time	tr		12		ns	$V_{GS}$ = 10 $V$ ,
Turn-off Delay Time	$t_{d(off)}$		76		ns	$R_G = 0 \Omega$
Fall Time	t <sub>f</sub>		14		ns	
Total Gate Charge	$Q_G$		133		nC	$V_{DD} = 48 \text{ V},$
Gate to Source Charge	$Q_{GS}$		38		nC	$V_{GS}$ = 10 $V$ ,
Gate to Drain Charge	$Q_{GD}$		38		nC	I <sub>D</sub> = 100 A
Body Diode Forward Voltage *1	$V_{F(S-D)}$			1.5	V	I <sub>F</sub> = 100 A, V <sub>GS</sub> = 0 V
Reverse Recovery Time	t <sub>rr</sub>		44		ns	I <sub>F</sub> = 50 A, V <sub>GS</sub> = 0 V,
Reverse Recovery Charge	Qrr		61		nC	di/dt = 100 A/μs

Note: \*1. Pulsed

#### **TEST CIRCUIT 1 AVALANCHE CAPABILITY**

#### TEST CIRCUIT 2 SWITCHING TIME





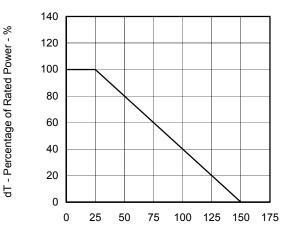
#### **TEST CIRCUIT 3 GATE CHARGE**

$$\begin{array}{c|c} D.U.T. \\ I_G = 2 \text{ mA} \\ \hline \end{array}$$

$$\begin{array}{c|c} PG. & \bigcirc \\ \end{array} \begin{array}{c} S & \Omega \\ \end{array} \begin{array}{c} \\ \end{array} \begin{array}{c} \\ \\ \end{array} \begin{array}{c}$$

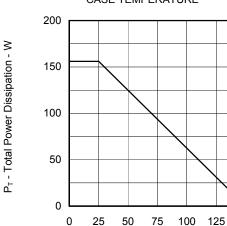
# Typical Characteristics ( $T_A = 25^{\circ}C$ )

DERATING FACTOR OF FORWARD BIAS SAFE OPERATING AREA



T<sub>C</sub> - Case Temperature - °C

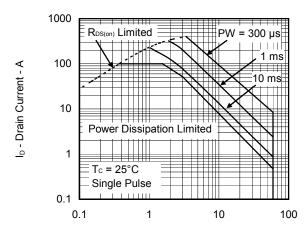
# TOTAL POWER DISSIPATION vs. CASE TEMPERATURE



T<sub>C</sub> - Case Temperature - °C

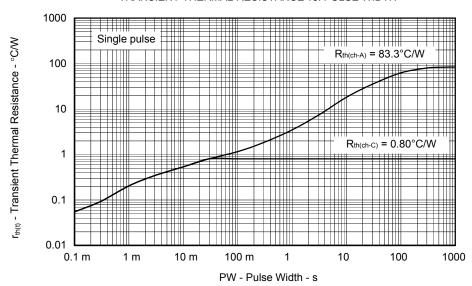
150

#### FORWARD BIAS SAFE OPERATING AREA



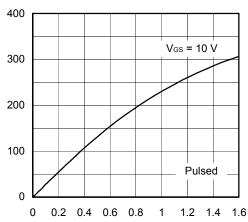
 $V_{\text{\scriptsize DS}}$  - Drain to Source Voltage - V

#### TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH



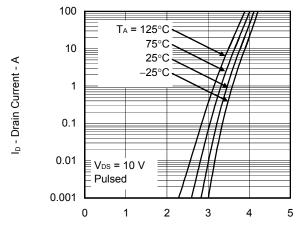
I<sub>D</sub> - Drain Current - A

#### DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



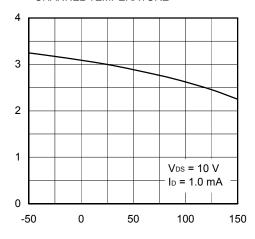
V<sub>DS</sub> - Drain to Source Voltage - V

#### FORWARD TRANSFER CHARACTERISTICS



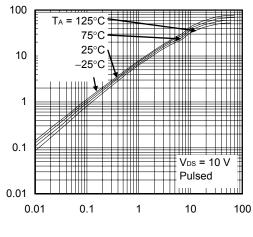
V<sub>GS</sub> - Gate to Source Voltage - V

#### GATE TO SOURCE CUT-OFF VOLTAGE vs. CHANNEL TEMPERATURE



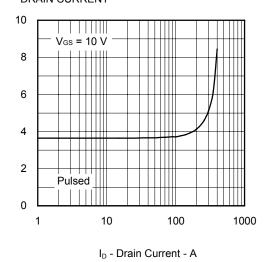
T<sub>ch</sub> - Channel Temperature - °C

#### FORWARD TRANSFER ADMITTANCE vs. DRAIN **CURRENT**

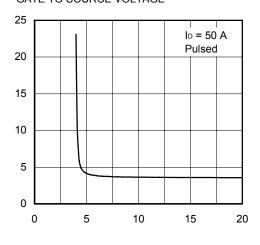


I<sub>D</sub> - Drain Current - A

#### DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



V<sub>GS</sub> - Gate to Source Voltage - V

 $\mathsf{R}_{\mathsf{DS}(\mathsf{on})}$  - Drain to Source On-state Resistance -  $m\Omega$ 

y<sub>fs</sub> | - Forward Transfer Admittance - S

 $R_{\text{DS}(\text{on})}$  - Drain to Source On-state Resistance -  $m\Omega$ 

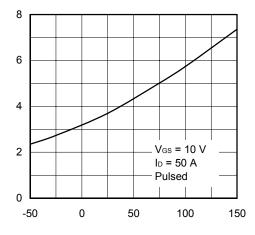
V<sub>GS(off)</sub> - Gate to Source Cut-off Voltage - V

 $R_{\text{DS(on)}}$  - Drain to Source On-state Resistance -  $m\Omega$ 

t<sub>d (on)</sub>, t<sub>r</sub>, t<sub>d (off)</sub>, t<sub>f</sub> - Switching Time - ns

I<sub>F</sub> - Diode Forward Current - A

#### DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE

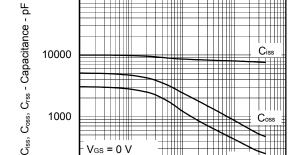


#### $T_{\text{ch}}$ - Channel Temperature - $^{\circ}C$

100000

100

0.01



f = 1.0 MHz

0.1

V<sub>DS</sub> - Drain to Source Voltage - V

1

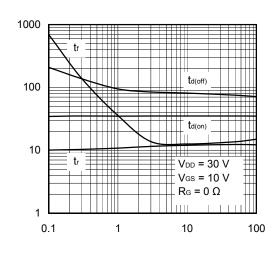
10

CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE

Ciss

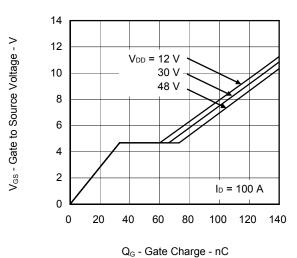
100

#### SWITCHING CHARACTERISTICS

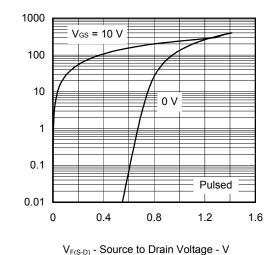


I<sub>D</sub> - Drain Current - A

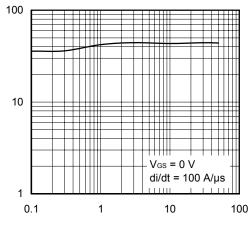
#### DYNAMIC INPUT CHARACTERISTICS



SOURCE TO DRAIN DIODE FORWARD VOLTAGE



REVERSE RECOVERY TIME vs. DIODE FORWARD CURRENT

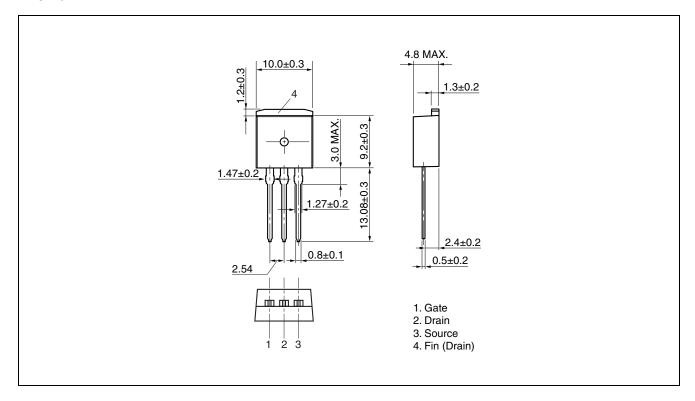


I<sub>F</sub> - Diode Forward Current - A

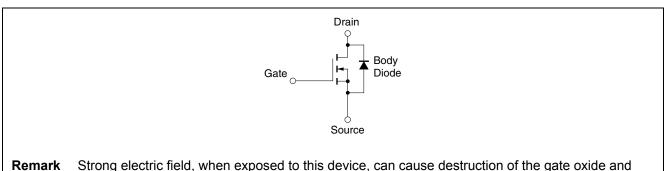
t<sub>rr</sub> - Reverse Recovery Time - ns

# Package Drawing (Unit: mm)

#### **TO-262**



# **Equivalent Circuit**



Strong electric field, when exposed to this device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred.

**Revision History** 

N0603N Data Sheet

		Description		
Rev.	Date	Page	Summary	
1.00	Nov 07, 2011	_	First Edition Issued	

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Renesas Electronics Europe Limited Dukes Meadow, Millboard Road, Boume End, Buckinghamshire, SL8 5FH, U.K Tel: +44-1628-585-100, Fax: +44-1628-585-900

Renesas Electronics Europe GmbH

Arcadiastrasse 10, 40472 Düsseldorf, Germany Tel: +49-211-65030, Fax: +49-211-6503-1327

Renesas Electronics (China) Co., Ltd.
7th Floor, Quantum Plaza, No.27 ZhiChunLu Haidian District, Beijing 100083, P.R.China
Tel: +86-10-2035-1155, Fax: +86-10-8235-7679

Renesas Electronics (Shanghai) Co., Ltd.
Unit 204, 205, AZIA Center, No. 1233 Lujiazui Ring Rd., Pudong District, Shanghai 200120, China
Tel: +86-21-5877-1818, Fax: +86-21-5887-7589

Renesas Electronics Hong Kong Limited
Unit 1601-1613, 16/F., Tower 2, Grand Century Place, 193 Prince Edward Road West, Mongkok, Kowloon, Hong Kong
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